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Abstract

Method for electroplating and contact projection arrangement

An explanation is given of, inter alia, a method for electroplating in which e.g. a copper layer (24) is patterned using a resist (26). A barrier layer (22) lying below the copper layer (24) is used for supplying the electroplating current in regions without the copper layer. The method makes it possible to produce high-quality soldering bumps.

(Figure 1A)